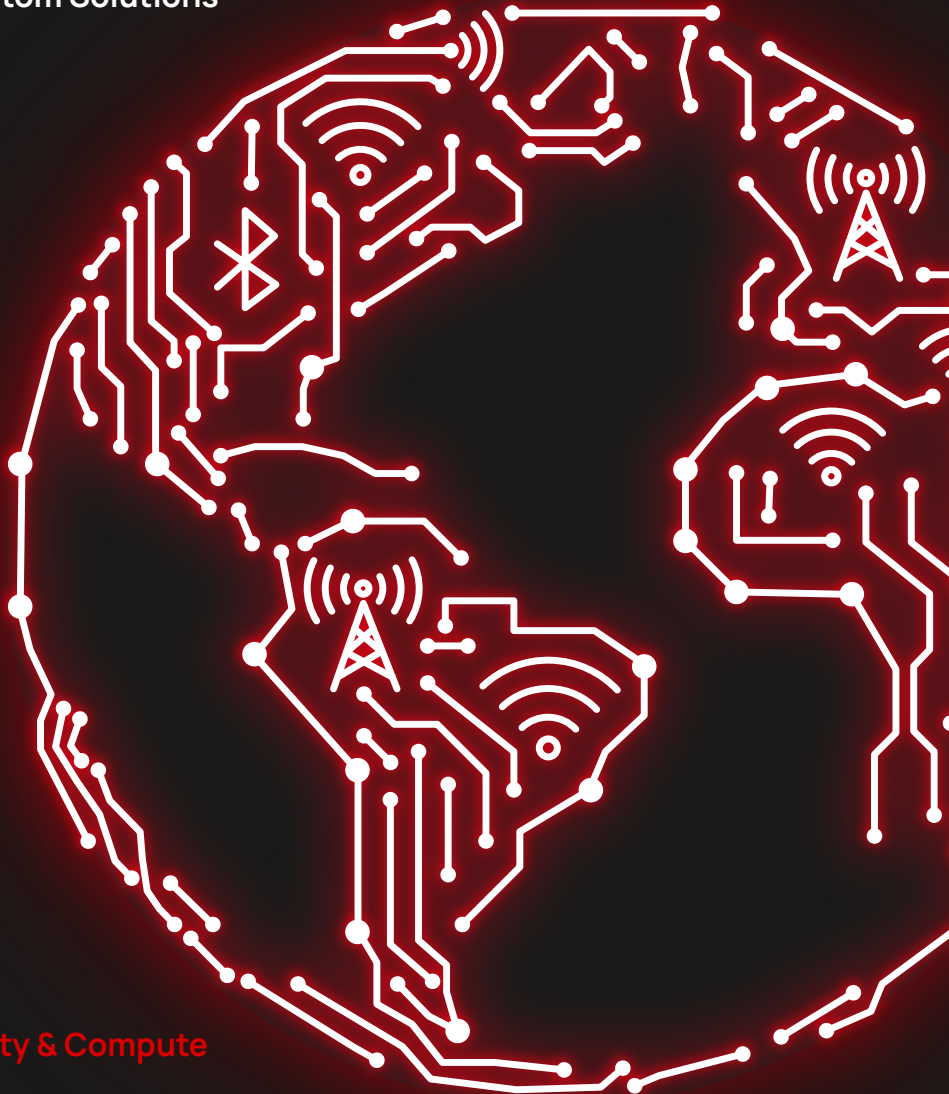


2026 Product Portfolio

Modules, SOMs, SBCs, Antennas,
IoT Devices and Custom Solutions



Simplify Connectivity & Compute

Simplify Connectivity & Compute

Ezurio engineers wireless connectivity and embedded compute solutions that power connected devices worldwide, backed by deep expertise in software, security, regulatory compliance, and long-term lifecycle support. Our portfolio includes RF modules, system-on-modules, single board computers, internal antennas, IoT devices, and custom solutions designed to accelerate development and reduce time to market.

To learn more about Ezurio, visit: www.ezurio.com

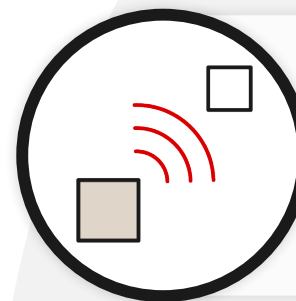
For the latest news or more information, visit:
[linkedin.com/company/ezurio-llc](https://www.linkedin.com/company/ezurio-llc)

What Problems does Ezurio Solve?



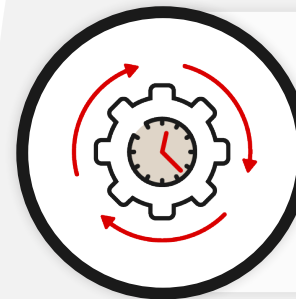
Security Breaches

Security breach can lead to loss of user trust, financial loss and regulatory penalties.



Lost Connectivity

Losing wireless connectivity can mean halted operations, missed data, and critical failures, risking productivity, security, and essential communication when it's needed most.



Time to Market

It's more than being first to market; it's about sustaining that advantage 5+ years out!



Navigating Regulatory

Ever faced delays or higher costs due to regulatory testing issues?

Wi-Fi Line Card

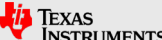


Ezurio offers certified Wi-Fi / Bluetooth modules that enable secure and reliable wireless connectivity, even in the harshest environments. Our modules are ideal for robust, business-critical connectivity in medical, industrial, and commercial settings where excellent RF performance, lower power consumption, simplified application development, and fast time to market are a must.

Modules not
actual size.



	Sona™ IF573	Sona™ IF513
Chipset	 AIROC™ CYW55573	 AIROC™ CYW55513
802.11 Standards	2x2 802.11a/b/g/n/ac/ax (Wi-Fi 6E)	1x1 802.11a/b/g/n/ac/ax (Wi-Fi 6E)
Frequency Bands	2.4 / 5 / 6 GHz	2.4 / 5 / 6 GHz
BT Standards	Bluetooth 6 - Dual Mode Classic (EDR) & LE	Bluetooth 6 - Dual Mode Classic (EDR) & LE
Type	M.2 1318 SMT M.2 2230 E-Key Module	M.2 1216 SMT M.2 2230 E-Key Module
Size (mm)	13 x 18 x 0.43 (M.2 1318) 22 x 30 x 2.7 (M.2 2230 E-Key)	12 x 16 x 1.75 (M.2 1216) 22 x 30 x 3.1 (M.2 2230 E-Key)
Antenna Diversity	2x2 Wi-Fi, 1x1 Bluetooth	1x1 MIMO
Data/Control	SDIO, PCIe, PCM/I2S, JTAG, UART	SDIO, PCIe, PCM/I2S, UART
Max PHY	MCS-11	MCS-11
Tx Power (dBm)	Up to +18	Up to +18
Rx Sensitivity (dBm)	-96	-97
Temp. Range	-40°C to +85°C	-40°C to +85°C
OS Support	Android, Linux, RTOS	Android, Linux, RTOS
Wi-Fi Security	WPA2-Personal, WPA2-Enterprise, WPA3-Personal, WPA3-Enterprise	WPA2-Personal, WPA2-Enterprise, WPA3-Personal, WPA3-Enterprise
Certifications	FCC, IC, CE, UKCA, MIC, RCM, Bluetooth SIG	FCC, IC, CE, UKCA, MIC, RCM, Bluetooth SIG
Software Support	Ezurio Connectivity Stack	Ezurio Connectivity Stack

Sona™ NX611	Sona™ TI351	Sona™ MT320
 IW611	 SimpleLink™ CC3351	 Filologic 320 (MT7921)
1X1 802.11a/b/g/n/ac/ax (Wi-Fi 6)	1x1 802.11a/b/g/n/ac/ax (Wi-Fi 6)	2x2 802.11a/b/g/n/ac/ax (Wi-Fi 6)
2.4 / 5 GHz	2.4 / 5 GHz	2.4 / 5 GHz
Bluetooth 5.3 - Dual Mode Classic (EDR) & LE	Bluetooth 5.4 - LE	Bluetooth 5.4 - Dual Mode Classic (EDR) & LE
SIP M.2 1216 SMT M.2 1218 SMT (Chip Ant.) M.2 2230 E-Key Module	M.2 1216 SMT (MHF4 Connector) M.2 1216 SMT (Chip Antenna) M.2 2230 E-Key Module	M.2 1420 SMT M.2 2230 E-Key Module
11 x 11 (SIP) 12 x 16 (M.2 1216 SMT Module) 12 x 18 (M.2 1218 SMT Module) 22 x 30 (M.2 E-Key Module)	12 x 16 x 1.75 (M.2 1216) 22 x 30 x 3.1 (M.2 2230 E-Key)	14 x 20 (M.2 1420) 22 x 30 (M.2 2230 E-Key)
1x1 SISO	1x1 SISO	2x2 Wi-Fi, 1x1 Bluetooth
SDIO, PCIe, PCM/I2S, DAC, ADC, HS- UART	SDIO, PCIe, PCM, UART	SDIO, PCIe, PCM/I2S, UART
MCS-11	MCS-7	MCS-11
Up to +18	Up to +18	Up to +18
-93	-98	-96
-40°C to +85°C	-40°C to +85°C	-40°C to +85°C
Android, Linux	Android, Linux	Android, Linux
WPA2-Personal, WPA2-Enterprise, WPA3-Personal, WPA3-Enterprise	WPA2-Personal, WPA2-Enterprise, WPA3-Personal, WPA3-Enterprise	WPA2-Personal, WPA2-Enterprise, WPA3-Personal, WPA3-Enterprise
FCC, IC, CE, UKCA, RCM, Bluetooth SIG	FCC, IC, CE, UKCA, MIC, KCC, RCM, Bluetooth SIG	FCC, IC, CE, UKCA, Bluetooth SIG
Ezurio Connectivity Stack	Ezurio Connectivity Stack	Mediatek Genio Linux / Android SDK

Wi-Fi Line Card

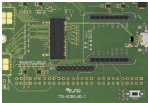


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Modules not actual size.



	Sterling-LWB5+	Sterling-LWB+	60 Series
Chipset	 Infineon CYW4373E	 Infineon CYW43439	 NXP 88W8997
MCU	N/A	N/A	N/A
802.11 Standards	802.11a/b/g/n/ac	802.11a/b/g/n	802.11a/b/g/n/ac
Frequency Bands	2.4 / 5 GHz	2.4 / 5 GHz	2.4 / 5 GHz
BT Standards	Bluetooth 5.2 - Dual Mode Classic (EDR) & BLE	Bluetooth 5.2 - Dual Mode Classic (EDR) & BLE	Bluetooth 5.1 - Dual Mode Classic (EDR) & BLE
Type	Surface Mount Module, M.2 2230 E-Key, USB-A Dongle	SiP Package, Surface Mount Module, M.2 2230 E-Key	SiP Package, M.2 2230-E Key (USB, SDIO, and PCIe variants)
Size (mm)	12 x 17 x 2.2 mm (SMT PCB) 22 x 30 x 2.9 mm (M.2 E-Key) 17.5 x 47 x 11.7 mm (USB)	12 x 12 x 3 mm (SiP) 21 x 15 x 4 mm (PCB) 22 x 30 x 2.3 (M.2 E-Key)	14 x 13 mm (SiP) 22 x 30 x 3.3 mm (M.2 E-Key)
Antenna Diversity	1x1 SISO	1x1 SISO	2x2 MIMO
Data/Control	SDIO, USB, PCM	SDIO, I2S, UART	SDIO, USB, PCM
Max PHY	MCS-9	MCS-7	MCS-9
Tx Power (dBm)	Up to +18	Up to +18	Up to +18
Rx Sensitivity (dBm)	-96	-94	-95
Temp. Range	-40°C to +85°C	-40°C to +85°C	-30°C to +85°C
OS Support	Android, Linux, RTOS	Android, Linux, RTOS	Android, Linux
Wi-Fi Security	WPA2/WPA3 Personal/Enterprise	WPA2/WPA3 Personal/Enterprise	WPA2/WPA3 Personal/Enterprise
Certifications	FCC, IC, CE, UKCA, MIC, KCC, TW, SRRC, RCM, BR, Bluetooth SIG	FCC, IC, CE, UKCA, MIC, RCM, BR, Bluetooth SIG	FCC, IC, CE, UKCA, MIC, KCC, RCM, Bluetooth SIG
Software Support Package	Ezurio Connectivity Stack, MODUS Toolbox and STM32CubeIDE IFX Expansion.	Ezurio Connectivity Stack, MODUS Toolbox and STM32CubeIDE IFX Expansion.	Ezurio Connectivity Stack, Summit Suite



Veda SL917	Veda IF912/913	M.2 2230 to STM32 Nucleo Adapter Card	
 Silicon Labs SiWx917	 CYW55912/CYW55913	All M.2 2230 Sona, LWB+, and LWB5+ Modules	Supported Modules
ARM® Cortex® M4 up to 180MHz	ARM® Cortex® M33 up to 192MHz (912) ARM® Cortex® M4 up to 192MHz (913)	Wi-Fi 6/6E, Wi-Fi 5, Wi-Fi 4	802.11 standards
802.11b/g/n/ax	1x1 802.11a/b/g/n/ac/ax (Wi-Fi 6 and Wi-Fi 6E)	Up to Bluetooth Core 6.0 (BDR + EDR + BLE)	BT Standards
2.4 GHz	2.4 / 5 GHz (IF912) 2.4 / 5 / 6 GHz (IF913)	M.2 2230 Key-E socket mikroBUS socket ST ZIO header pins	Physical interface
Bluetooth 5.4 - Single Mode BLE	Bluetooth v5.4 Dual Mode	92 x 70	Size (mm)
Surface Mount Module WITH Embedded MCU	SiP	Dependent on wireless module	Tx Power (dBm)
16 x 21.1 x 2.3 (SMT PCB)	7 x 11 x 1.4	Dependent on wireless module	Rx Sensitivity (dBm)
1x1 SISO	1x1 MIMO	Current measurement points, flexible power supply (micro USB or from Nucleo board)	Additional
UART, I2C/PCM, SDIO, DAC/ADC, SPI	UART, I2C/PCM, SDIO, DAC, SPI	MODUS Toolbox	Software Support Package
MCS-7	MCS-11		
Up to +17	Up to +24		
-94.5	Up to -97		
-40°C to +85°C	-40 to +85		
TBD	ThreadX (SOC), Linux (NCP)		
WPA2/WPA3 Personal/Enterprise	WPA2/WPA3 Personal/Enterprise		
FCC, IC, CE, UKCA, MIC, KCC, RCM, NCC, SRRC, Bluetooth SIG	FCC, IC, CE, UKCA, RCM, MIC, Bluetooth SIG		
Simplicity Studio™, STM32 CUBE IDE, NXP MCUXpresso IDE, FreeRTOS (NCP)	MODUS Toolbox		

Bluetooth LE Line Card



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Modules not actual size.																					
				BL54LM20A			BL54LM20B			BL54L15 / BL54L15µ			BL54L10			Lyra 24 Series			Lyra Series		
Chipset																					
				Nordic nRF54LM20A SoC			Nordic nRF54LM20B Soc			Nordic nRF54L15 SoC			Nordic nRF54L10 SoC			Silicon Labs EFR32BG24 SoC			Silicon Labs EF32BG22 SoC		
Wireless				BT LE Core 6.0 / 802.15.4 / NFC			BT LE Core 6.0 / 802.15.4 / NFC			BT6 LE / 802.15.4 / NFC			BT 6 LE / 802.15.4 / NFC			BT 5.4 LE			BT 5.3 LE		
Type (Flash/RAM)				SMT with onboard MCU (1x ARM Cortex-M33, 1x RISC-V, 2 MB Flash, 512 KB RAM)			SMT with onboard MCU (1x ARM Cortex-M33, 1x RISC-V, 2 MB Flash, 512 KB RAM)			SMT with onboard MCU (1x ARM Cortex-M33, 1x RISC-V, 1.5 MB Flash, 256 KB RAM)			SMT with onboard MCU (1x ARM Cortex-M33, 1x RISC-V, 1 MB Flash, 192 KB RAM)			SMT or USB with onboard MCU (ARM Cortex-M33, 1536 KB flash, 256 KB RAM)			SMT with onboard MCU (ARM Cortex-M33, 512 KB flash, 32 KB RAM)		
Size (mm)				11 x 8 x 1.8 (Module)			11 x 8 x 1.8 (Module) 15 x 26 x 6 (USB)			10 x 14 x 1.6 (BL54L15) 6.3 x 7.9 x 1.6 (BL54L15µ)			10 x 14 x 1.6			7 x 7 x 1.18 (SiP) 12.9 x 15.0 x 2.15 (PCB) 12 x 50.74 x 11 (USB)			6 x 6 x 1.1 (SiP) 12.9 x 15 x 2.2 (PCB)		
Antenna Options				MHF4 connector / Chip Antenna (Module)			MHF4 connector / Chip Antenna (Module) Integrated Antenna (USB)			Integrated PCB trace or MHF4 connector / Chip Antenna or MHF4 Connector			Integrated PCB trace antenna OR ext. via MHF4 connector			Integrated (PCB and USB), Integrated or external (SiP)			Integrated (PCB), Integrated or external (SiP)		
Data/Control				UART, SPI, HS-SPI, TWI, ADC, I2S, PWM, TIMER, QDEC, RTC, WDT, NFC A-Tag, TEMP, Comparator, LPCOMP			UART, SPI, HS-SPI, TWI, ADC, I2S, PWM, TIMER, QDEC, RTC, WDT, NFC A-Tag, TEMP, Comparator, LPCOMP			UART, SPI, TWI, ADC, I2S, PWM, TIMER, QDEC, RTC, WDT, NFC A-Tag, TEMP, Comparator, LPCOMP			UART, NFC A-Tag, SPI, TWI, HS-SPI, I2S, PWM, ADC, GPIO, QDEC, WDT, LPCOMP			UART, EUART, I2C, SPI, ADC, GPIO, PWN, Counter, Timer, Watchdog, PRS (module)			UART, I2C, SPI, ADC, GPIO, PWM, PDM, Counter, Timer, Watchdog, PRS		
Tx Power (dBm)				Up to +8 dBm			Up to +8 dBm			Up to +7 dBm (BL54L15) Up to +8 dBm (BL54L15µ)			Up to +7 dBm			Up to +10 or +20 (PCB) Up to +10 (SiP) Up to +20 (USB)			Up to +8 dBm (PCB) Up to +6 dBm (SiP)		
Rx Sensitivity (dBm)				Up to -95.5 dBm			Up to -95.5 dBm			Up to -106 dBm			Up to -106 dBm			Up to -106.5 dBm (PCB) Up to -105.1 (SiP) (USB)			Up to -98.9 dBm (PCB) Up to -98.6 dBm (SiP)		
Temp Range				-40°C to +105°C			-40°C to +105°C			-40°C to +105°C			-40°C to +105°C			-40°C to +105°C			-40°C to +105°C		
Software / Firmware				Canvas Software Suite (MicroPython), Nordic SDK, Zephyr RTOS			Canvas Software Suite (MicroPython), Nordic SDK, Zephyr RTOS			Canvas Software Suite (MicroPython), Nordic SDK, Zephyr RTOS			Canvas Software Suite (MicroPython), Nordic SDK, Zephyr RTOS			Canvas Software Suite (MicroPython) AT Command Set or full C Code			AT Command Set, Wireless Xpress, or full C Code		
Profiles / Services Supported				Any supported via Canvas/Nordic/Zephyr			Any supported via Canvas/Nordic/Zephyr			Any supported via Canvas/Nordic/Zephyr			Any supported via Canvas/Nordic/Zephyr			AT Commands, or any supported via Silicon Labs SDK			AT Commands, or any supported via Wireless Xpress / Silicon Labs SDK		
Additional Features				Higher onboard flash than previous BL54L Series			Adds integrated Axon MPU for onboard AI/ML			BL54L15 is pin-compatible with BL54L10			BL54L10 is pin-compatible with BL54L15			Intelligent power schemes, deep sleep mode, secure boot, ARM TrustZone, HW cryptographic accelerator			Intelligent power schemes, deep sleep mode, secure boot, ARM TrustZone, HW cryptographic accelerator		
Certifications				FCC, IC, CE, UKCA, MIC, KCC, RCM, Bluetooth SIG			FCC, IC, CE, UKCA, MIC, KCC, RCM, Bluetooth SIG			FCC, IC, CE, UKCA, MIC, KCC, RCM, Bluetooth SIG			FCC, IC, CE, UKCA, MIC, KCC, RCM, Bluetooth SIG			FCC, IC, CE, UKCA, MIC, KCC, RCM, Bluetooth SIG			FCC, IC, CE, UKCA, MIC, KCC, RCM, Bluetooth SIG		

Bluetooth LE Line Card



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Modules not actual size.

	BL5340 Series	BL5340PA Series
Chipset	 Nordic nRF5340 SoC	 Nordic nRF5340 SoC + Nordic nRF21540 FEM
Wireless	BT 5.x LE + NFC + Thread	BT 5.x LE + NFC + Thread
Type (Flash/RAM)	SMT w/ dual Cortex M33 (App processor 1MB/512KB. Network processor 256KB/64KB)	SMT w/ dual Cortex M33 (App processor 1MB/512KB. Network processor 256KB/64KB)
Size (mm)	15 x 10 x 2.2	21 x 10 x 2.2
Antenna Options	Internal Antenna OR External via trace pin	Internal Antenna OR External (MHF4)
Data/Control	USB, UART, QSPI, GPIO, ADC, PWM, PDM, QDEC, FREQ output, I ² S, I ² C, SPI, Comparator, Low Power Comparator	USB, UART, QSPI, GPIO, ADC, PWM, PDM, QDEC, FREQ output, I ² S, I ² C, SPI, Comparator, Low Power Comparator, Power Amplifier
Tx Power (dBm)	Up to +3 dBm	Up to +18.5 dBm
Rx Sensitivity (dBm)	Up to -98 dBm	Up to -108.5dBm
Temp Range	-40°C to +105°C	-40°C to +105°C
Software/Firmware	Canvas Software Suite (MicroPython), Zephyr RTOS, Nordic nRF Connect	Canvas Software Suite (MicroPython), Zephyr RTOS, Nordic nRF Connect
Profiles / Services Supported	Any services available via Canvas/Nordic/Zephyr	Any services available via Canvas/Nordic/Zephyr
Additional Features	BLE Mesh, AoA/AoD, LE Audio / Isochronous Channels, LE Coded (Long Range)	BLE Mesh, AoA/AoD, LE Audio / Isochronous Channels, LE Coded (Long Range)
Certifications	FCC, IC, CE, UKCA, MIC, RCM, Bluetooth SIG	FCC, IC, CE, UKCA, RCM, Bluetooth SIG

BL654 Series (includes USB adapter)	BL654PA Series	BL653/ BL653μ Series
 Nordic nRF52840	 Nordic nRF52840 + Skyworks PA SKY66112-11	 Nordic nRF52833
BT 5.x LE + NFC + Thread	BT 5.x LE + NFC + Thread	BT 5.x LE + NFC + Thread
SMT with onboard MCU (ARM Cortex M4F, 1MB/256k)	SMT with onboard MCU (ARM Cortex M4F, 1MB/256k)	SMT with onboard MCU (ARM Cortex M4F, 512KB/128KB)
15 x 10 x 2.2 (module) 18.4 x 50.7 x 11 (USB)	22 x 10 x 2.2	15x10x2.2 (BL653) 6.3x5.6x1.6 (BL653μ/trace pad) 6.3x8.6x1.6 (BL653μ/int. antenna)
Internal Antenna OR External (MHF4)	Internal Antenna OR External (MHF4)	Internal Ant. OR External (trace pin)
USB, UART, GPIO, ADC, PWM, PDM, FREQ output, I ² S, I ² C, SPI	UART, GPIO, ADC, PWM, PDM, FREQ output, I2S, I2C, SPI, QSPI	UART, GPIO, ADC, PWM, PDM, FREQ output, I2C, I2S, SPI, NFC, USB
Up to +8 dBm	Up to +18 dBm	Up to +8 dBm
Up to -103 dBm	Up to -107 dBm	Up to -103 dBm (BL653) Up to -103 dBm (BL653μ)
-40°C to +85°C	-40° to +85° C	-40°C to +105°C
Canvas Software Suite (MicroPython), AT Command Set, smartBASIC OR use Nordic SDK, Zephyr	AT Command Set, smartBASIC OR use Nordic SDK, Zephyr	AT Command Set, smartBASIC OR use Nordic SDK, Zephyr
Any services available via Canvas/Nordic/Zephyr	Any available via smartBASIC/Nordic/Zephyr	Any available via smartBASIC/fNordic/Zephyr
BLE Mesh Packaged USB Adapters	BLE Mesh Ultra Long Range	BLE Mesh Extended Temp Range
FCC, IC, CE, UKCA, MIC, KCC, RCM, Bluetooth SIG	FCC, IC, RCM, KCC, Bluetooth SIG	FCC, IC, CE, UKCA, MIC, KCC, RCM, Bluetooth SIG

Bluetooth Dual Mode Line Card



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Modules not actual size.



	Vela IF820 Series	Vela IF310
Chipset	 Infineon CYW20820	 CYW55310
Wireless Standards	Dual-Mode BT 5.4	BT 6 Classic / LE
Type (Flash/RAM)	SMT or USB Adapter (256 kb Flash/176 kB RAM/ 1 MB ROM)	SMT with onboard MCU (ARM Cortex-M33, 2048 KB flash, 768 KB RAM)
Size (mm)	7.5 x 7.5 x 2.15 mm (External Antenna) 9.3 x 12.5 x 2.15 mm (Chip Antenna) 18.39 x 50.74 x 11 mm (USB Adapter)	12 x 16 x 1.6
Antenna Options	Chip Antenna, MHF4 Connector, or packaged USB adapter	Integrated, MHF4, Trace Pin
Data/Control	UART, GPIO, I2C, PCM, SPI, ADC, PWM, RTC, WDT	UART, MCI, PDM, TDM, I2S, PCM, GPIO
Tx Power (dBm)	Up to +10 dBm	Up to +10 dBm
Rx Sensitivity (dBm)	Up to -93.0 dBm	Up to -110 dBm (BLE), Up to -97 dBm (Classic)
Temp Range	-40°C to +85°C	-40°C to +85°C
Software/Firmware	EZ-Serial, HCI UART, or C Code via Modus ToolBox	External BT stack, Modus Toolbox
Profiles / Services Supported	EZ-Serial (SPP) Any supported by chosen BT stack	Any Supported via BT stack
Additional Features	Simultaneous BT and BLE connections. Packaged USB Adapters	LE Audio, LC3 Codec Classic Audio Hosted or Hostless Mode
Certifications	FCC, IC, CE, UKCA, MIC, KCC, RCM, Bluetooth SIG	FCC, IC, CE, UKCA, MIC, KCC, RCM, Bluetooth SIG



	BT850/BT860 Series	BT851 USB Adapter
Chipset	 Infineon CYW20704 A2	 Infineon CYW20704 A2
Wireless Standards	Dual-Mode BT5.2	Dual-Mode BT5.2
Type (Flash/RAM)	SMT with HCI Interface	USB HCI Adapter
Size (mm)	8.5 x 12.9 x 2.2	50.7 x 18.4 x 11
Antenna Options	Internal Antenna OR External via trace pad	Internal Antenna
Data/Control	USB, HCI (BT850) UART, HCI (BT860)	USB, HCI
Tx Power (dBm)	Up to +8 dBm	Up to +8 dBm
Rx Sensitivity (dBm)	-94 dBm	-94 dBm
Temp Range	-30°C to +85°C	-30°C to +85°C
Software/Firmware	Any external BT software stack via HCI	Any external BT software stack via HCI
Profiles / Services Supported	Any supported by chosen BT stack	Any supported by chosen BT stack
Additional Features	Support for Searan Dotstack.	Support for Searan Dotstack.
Certifications	FCC, IC, CE, UKCA, MIC, KCC, MIC, RCM, Bluetooth SIG	FCC, IC, CE, UKCA, MIC, Bluetooth SIG

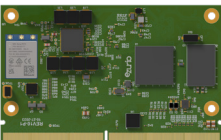
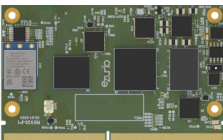
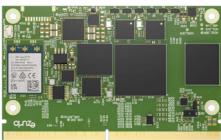
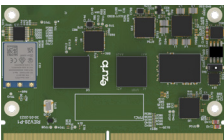
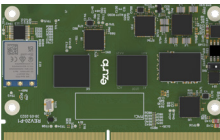
System-on-Modules (SOMs)



SMARC SOMs

Ezurio embedded system-on-modules (SOMs) deliver highly scalable embedded processing solutions with onboard Wi-Fi and Bluetooth. Built on the latest processors and wireless, and utilizing our long term software support, our SOMs provide a secure, smart, connected IoT platform for the most demanding applications.

Modules not actual size.



	Nitrogen91 SMARC	Nitrogen93 SMARC
Processor	 i.MX 91	 i.MX 93
MPU	1x Cortex®-A55 @ up to 1.4 GHz	2x Cortex®-A55 @ up to 1.7 GHz
MCU	N/A	1x Cortex®-M33 core @ 250 MHz
Wireless Onboard	Sona Wi-Fi / BT Range: M.2 1216	Sona Wi-Fi / BT Range: M.2 1216
RAM	1GB/2GB LPDDR4	1GB/2GB LPDDR4
Storage	16GB	16GB
Display	N/A	MIPI-DSI, LVDS
Camera	N/A	1x MIPI-CSI
Co-Processors	N/A	2D GPU, NPU
Audio	2x I2S	2x I2S
Form Factor	SMARC	SMARC
Additional Interfaces	2x USB 2, 2x GbE, 2x CAN/CAN FD 1x SDIO/eMMC 12C, SPI, UART, GPIO	2x USB 2, 2x GbE, 2x CAN/CAN FD 1x SDIO/eMMC 12C, SPI, UART, GPIO
Size	82 x 50 mm	82 x 50 mm
Operating Temperature	0 to +70C or -40 to +85C	0 to +70C or -40 to +85C
Certifications	As per Sona wireless module	As per Sona wireless module

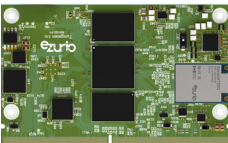
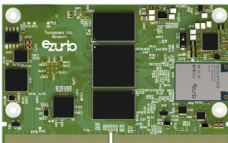
	Nitrogen95 SMARC	Nitrogen8M Plus SMARC	Nitrogen8M Mini SMARC
Processor	 i.MX 95	 i.MX 8M Plus	 i.MX 8M Mini
MPU	6x Cortex®-A55 @ up to 1.8 GHz	4x Cortex®-A53 @ up to 1.8 GHz	4x Cortex®-A53 @ up to 1.8 GHz
MCU	1x Cortex®M7 & 1x Cortex®-M33	1x Cortex®-M7 core @ 800 MHz	1x Cortex®-M4 @ 400 MHz
Wireless Onboard	Sona Wi-Fi / BT Range: M.2 1216	Sona Wi-Fi / BT Range: M.2 1216	Sona Wi-Fi / BT Range: M.2 1216
RAM	4GB/8GB/16GB LPDDR4	2GB/4GB/8GB LPDDR4	1GB/2GB/4GB LPDDR4
Storage	16GB	16GB	16GB
Display	MIPI-DSI, LVDS	MIPI-DSI, HDMI, LVDS	MIPI-DSI. LVDS
Camera	1x MIPI-CSI	2x MIPI-CSI	1x MIPI-CSI
Co-Processors	3D/2D GPU, NPU,	3D/2D GPU, VPU, NPU	3D/2D GPU, VPU
Audio	2x I2S	2x I2S	2x I2S
Form Factor	SMARC	SMARC	SMARC
Additional Interfaces	2x PCIe, 3x USB 2, 2x USB 3.1, 2x GbE, 2x CAN/CAN FD 1x SDIO/eMMC 12C, SPI, UART, GPIO	1x PCIe, 2x USB3/USB2, 2x USB2, 2x GbE, 2x CAN/CAN FD 1x SDIO/eMMC 12C, SPI, UART, GPIO	1x PCIe, 3x USB2, 1x GbE, 1x SDIO/eMMC, 12C, SPI, UART, GPIO
Size	82 x 50 mm	82 x 50 mm	82 x 50 mm
Operating Temperature	0 to +70C or -40 to +85C	0 to +70C or -40 to +85C	0 to +70C or -40 to +85C
Certifications	As per Sona wireless module	As per Sona wireless module	As per Sona wireless module

System-on-Modules (SOMs)

SMARC SOMs

Ezurio embedded system-on-modules (SOMs) deliver highly scalable embedded processing solutions with onboard Wi-Fi and Bluetooth. Built on the latest processors and wireless, and utilizing our long term software support, our SOMs provide a secure, smart, connected IoT platform for the most demanding applications.

Modules not actual size.

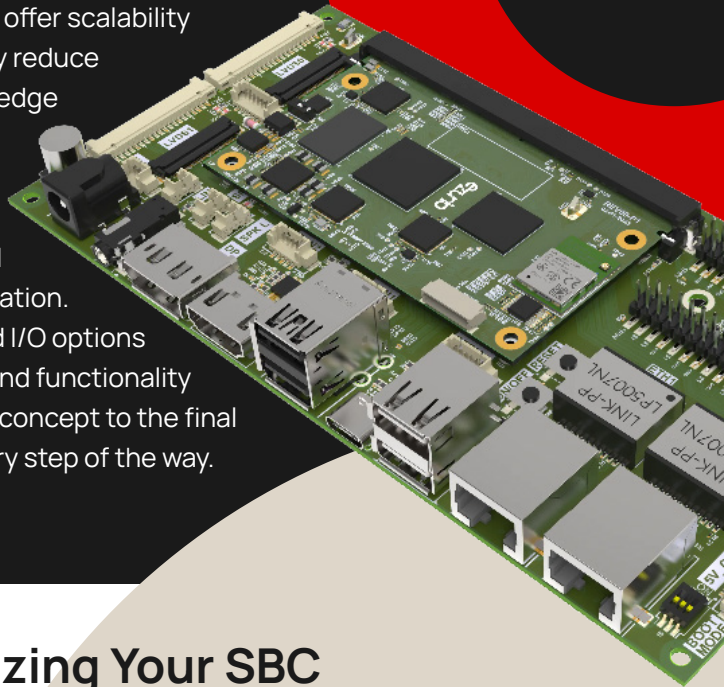


	Tungsten700 SMARC	Tungsten510 SMARC
Processor	MEDIATEK Genio 700	MEDIATEK Genio 510
MPU	2x Cortex-A78 @ 2.2 GHz 6x Cortex-A55 @ 2.0 GHz	2x Cortex-A78 @ up to 2.0 GHz 4x Cortex-A55 @ up to 2.0 GHz
MCU	N/A	N/A
Wireless Onboard	Sona MT320: Wi-Fi 6, Bluetooth 5.4	Sona MT320: Wi-Fi 6, Bluetooth 5.4
RAM	4GB/8GB LPDDR4	4GB /8GB LPDDR4
Storage	16GB	16GB
Display	2x MIPI-DSI, DisplayPort, Embedded DisplayPort, HDMI	2x MIPI-DSI, DisplayPort, Embedded DisplayPort, HDMI
Camera	2x MIPI-CSI	2x MIPI-CSI
Co-Processors	VPU, Audio DSP, Arm Mali-G57 MC3 GPU, NPU	VPU, Audio DSP, Arm Mali-G57 MC2 GPU, NPU
Audio	2x I2S	2x I2S
Form Factor	SMARC	SMARC
Additional Interfaces	1x PCIe, 2x USB3/USB2, 3x USB2, 2x GbE, 1x SDIO/eMMC, I2C, SPI, UART, GPIO	1x PCIe, 2x USB3/USB2, 3x USB2, 2x GbE, 1x SDIO/eMMC, I2C, SPI, UART, GPIO
Size	82 x 50 mm	82 x 50 mm
Operating Temperature	0 to +70C (Commercial) -40 to +85C (Industrial)	0 to +70C (Commercial) -40 to +85C (Industrial)
Certifications	As per Sona wireless module	As per Sona wireless module

Custom SBC Solutions

Unlock infinite possibilities, one custom SBC at a time.

Accelerate your path to production with custom single board computers (SBC). Custom SBCs not only offer scalability for future upgrades, but also significantly reduce time-to-market, providing a competitive edge in rapidly evolving markets. By leveraging a system-on-module (SOM) and a carrier board, whether it's our design or yours, the platform can be customized to meet the specific needs of your application. Choose the right processor, memory, and I/O options to perfectly align with the performance and functionality demands of your project. From the initial concept to the final product, we partner closely with you every step of the way.



6 Benefits of Customizing Your SBC

The versatility and portability of single board computers (SBC) contribute significantly to their effectiveness in meeting the demands of various embedded applications such as industrial automation, automotive control systems, medical devices, and IoT deployments. These compact computing devices enable engineers to rapidly prototype and deploy embedded solutions, fostering innovation in various industries.

- ✓ Tailored Performance
- ✓ Cost Optimization
- ✓ Form Factor and Size
- ✓ Power Efficiency
- ✓ Integration of Specialized Hardware
- ✓ Enhanced Security

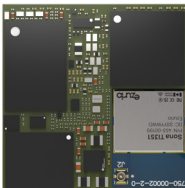
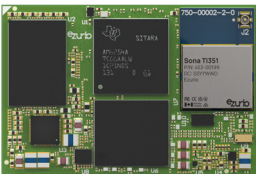
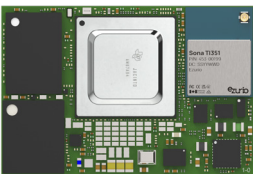
System-on-Modules (SOMs)



Open Standard Module (OSM) Modules

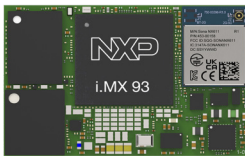
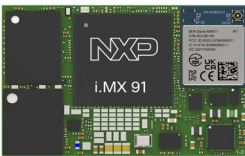
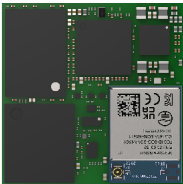
Ezurio embedded system-on-modules (SOMs) deliver highly scalable embedded processing solutions with onboard Wi-Fi and Bluetooth. Built on the latest processors and wireless, and utilizing our long term software support, our SOMs provide a secure, smart, connected IoT platform for the most demanding applications.

Modules not actual size.



	CarbonAM67 OSM-MF	CarbonAM62 OSM-MF	CarbonAM62L OSM-SF
Processor	 TEXAS INSTRUMENTS AM67 Jacinto	 TEXAS INSTRUMENTS AM62 Sitara	 TEXAS INSTRUMENTS AM62L Sitara
MPU	4x Cortex-A53 @ up to 1.4 GHz	4x Cortex-A53 @ up to 1.4 GHz	2x Cortex-A53 @ up to 1.25 GHz
MCU	3x Cortex-R5F @ up to 800 MHz	1x Cortex-M4F @ up to 400 MHz 1x Cortex-R5F @ up to 400 MHz	N/A
Wireless	Sona TI351: Wi-Fi 6, Bluetooth LE 5.4 (optional IF513)	Sona TI351: Wi-Fi 6, Bluetooth LE 5.4 (optional IF513, 60-SIP)	Sona TI351: Wi-Fi 6, Bluetooth LE 5.4 (optional IF513)
RAM	2GB or 4GB LPDDR4	1GB or 2GB LPDDR4	512 MB, 1GB or 2GB LPDDR4
Storage	16GB	16GB	Up to 1 GB flash onboard Up to 128GB eMMC offboard
Display	MIPI-DSI, LVDS, RGB	LVDS, RGB	MIPI-DSI
Camera	4x MIPI-CSI	1x MIPI-CSI	N/A
Co-Processors	3D/2D GPU, VPU, NPU, DSP, ISP	3D/2D GPU, PRUSS	N/A
Audio	2x I2S	2x I2S	1x I2S
Form Factor	OSM-MF	OSM-MF	OSM-SF
Additional Interfaces	1x PCIe, 1x USB3.1, 1x USB2, 2x GbE, 2x CAN-FD, 1x SDIO/eMMC, I2C, SPI, UART, GPIO	2x USB2, 2x GbE, 2x CAN-FD, 1x SDIO/eMMC, I2C, SPI, UART, GPIO	2x USB2, 2x GbE, 2x CAN-FD, 1x SDIO/eMMC, ADC, I2C, SPI, UART, GPIO
Size	45 x 30 mm	45 x 30 mm	30 x 30 mm
Operating Temperature	0 to +70C (Commercial) -40 to +85C (Industrial)	0 to +70C (Commercial) -40 to +85C (Industrial)	0 to +70C (Commercial) -40 to +85C (Industrial)
Certifications	All via wireless module	All via wireless module	All via wireless module

Modules not actual size.

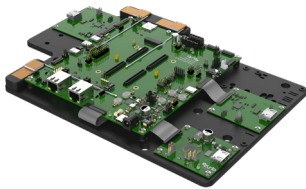
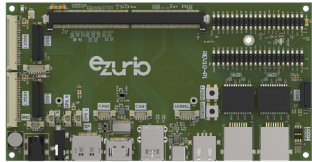


	Nitrogen i.MX91 OSM-SF	Nitrogen i.MX91 OSM-MF	Nitrogen i.MX93 OSM-MF
Processor	 i.MX 91	 i.MX 91	 i.MX 93
MPU	1x Cortex-A55 @ up to 1.4 GHz	1x Cortex®-A55 @ up to 1.4 GHz	2x Cortex®-A55 @ up to 1.7 GHz
MCU	N/A	N/A	1x Cortex®-M33 core @ 250 MHz
Wireless	Sona NX611: Wi-Fi 6, Bluetooth LE 5.4 (optional IF513)	Sona NX611: Wi-Fi 6, Bluetooth LE 5.4 (optional IF513)	Sona NX611: Wi-Fi 6, Bluetooth LE 5.4 (optional IF513)
RAM	1GB or 2GB LPDDR4	1GB or 2GB LPDDR4	1GB or 2GB LPDDR4
Storage	16GB	16GB	16GB
Display	MIPI-DSI	MIPI-DSI	MIPI-DSI, LVDS
Camera	N/A	N/A	1x MIPI-CSI
Co-Processors	N/A	N/A	2D GPU, NPU
Audio	N/A	2x I2S	2x I2S
Form Factor	OSM-SF	OSM-MF	OSM-MF
Additional Interfaces	1x USB2, 1x GbE, 1x CAN-FD, 1x SDIO/eMMC, I2C, SPI, UART, GPIO	2x USB 2, 2x GbE, 2x CAN/CAN FD, 1x SDIO/eMMC, I2C, SPI, UART, GPIO	2x USB 2, 2x GbE, 2x CAN/CAN FD, 1x SDIO/eMMC, I2C, SPI, UART, GPIO
Size	30 x 30 mm	45 x 30 mm	45 x 30 mm
Operating Temperature	0 to +70C (Commercial) -40 to +85C (Industrial)	0 to +70C or -40 to +85C	0 to +70C or -40 to +85C
Certifications	All via wireless module	All via wireless module	All via wireless module

Generic Evaluation Kits

Generic Evaluation kits and Carrier boards from Ezurio provide the host platform for your SMARC or OSM-based device. They provide many external interfaces, including data, audio/video, camera, wired and wireless networking, power supply connectors and more, SBCs provide the complete platform for your embedded design. Looking for the perfect fit for your design? Talk to us about our customization options – we can design the perfect custom board for your application with everything that you need, and nothing that you don't.

Modules not actual size.



	Universal SMARC Carrier	Generic OSM Evaluation Kit
Processor	Add your choice of SMARC SOM to carrier to evaluate	Add interposer kit (adapter kit) for your choice of OSM SOM to kit to evaluate
MPU	MPU onboard SMARC SOM	MPU onboard OSM SOM
MCU	MCU onboard SMARC SOM	MCU onboard OSM SOM
Wireless Protocol	Wireless onboard SMARC SOM	Wireless onboard OSM SOM Interposer Kit
Interfaces	x2 4-lane MIPI display, 2 x 4-lane MIPI camera, x2 GB Ethernet, PCIe, USB 3.0/2.0, Stereo Audio (headphone/speaker) I2C, SPI, CAN, GPIO	1x LVDS, 1x RGB, 1x 4-lane MIPI display, 4x 4-lane MIPI camera, 2x GB Ethernet, PCIe, USB 3.0/2.0, Stereo Audio (headphone/speaker) I2C, SPI, CAN, GPIO
Size (mm)	168 x 87 mm	180 x 160 x 20.48 mm
Operating Temperature	0 to +70 °C	-40 to 85 °C

Evaluation Kits



Our SMARC and OSM SOM Evaluation kits provide a complete prototyping platform to design around our NXP-based and TI-based SOMs. They're bundled with a touchscreen display, a carrier board to expose all I/O, built-in Wi-Fi and Bluetooth, and offer support for additional displays or camera inputs. Start developing with our EVKs today. Visit the product pages below to find technical documentation, including quick start guides to support rapid out-of-the-box application development.



	Nitrogen93 i.MX93 EVK	Nitrogen95 i.MX95 EVK	Carbon AM62 OSM EVK	Carbon AM67 OSM EVK	
	 i.MX93	 i.MX95	 TEXAS INSTRUMENTS AM62 Sitara	 TEXAS INSTRUMENTS AM67 Jacinto	Processor
	2x Cortex®-A55 @ up to 1.7 GHz	6x Cortex®-A55 @ up to 1.8 GHz	4x Cortex-A53 @ up to 1.4 GHz	4x Cortex-A53 @ up to 1.4 GHz	MPU
	1x Cortex®-M33 core @ 250 MHz	1x Cortex®M7 & 1x Cortex®-M33	1x Cortex-M4F @ 400 MHz 1x Cortex-R5F @ 400 MHz	3x Cortex-R5F @ 800 MHz	MCU
	NXP eIQ® Neutron N3-1024S AI Accelerator	NXP eIQ® Neutron N3-1024S AI Accelerator	N/A	N/A	NPU
	7-inch touch display/stand	7-inch touch display/stand	7-inch touch display/stand	7-inch touch display/stand	Display
	None	Arducam x-ISP 3.8MP 4K Camera (optional)	Arducam x-ISP 3.8MP 4K Camera (optional)	Arducam x-ISP 3.8MP 4K Camera (optional)	Camera
	Wi-Fi 6 + BT 5.4 (NX611)	Wi-Fi 6 + BT 5.4 (NX611)	Wi-Fi 6 + BT 5.4 (TI351)	Wi-Fi 6 + BT 5.4 (TI351)	Wireless Protocol
	2x Gb Ethernet, LVDS, MIPI-CSI, USB, CAN, UART, SPI, I2C, GPIO, microSD, speakers, headphone, mic, line in	2x Gb Ethernet, LVDS, MIPI-CSI, USB, CAN, UART, SPI, I2C, GPIO, microSD, speakers, headphone, mic, line in	2x USB2, 2x GbE, 2x CAN-FD, 1x SDIO/eMMC, I2C, SPI, UART, GPIO	1x PCIe, 1x USB3.1, 1x USB2, 2x GbE, 2x CAN-FD, 1x SDIO/eMMC, I2C, SPI, UART, GPIO	Interfaces
	SMARC + NX611, touch screen, stand, carrier, FlexPIFA, Cables	SMARC + NX611, touch screen, stand, carrier, FlexPIFA, Cables, Camera (optional)	OSM + TI351, touch screen, stand, carrier, FlexPIFA, Cables, Camera (optional)	OSM + TI351, touch screen, stand, carrier, FlexPIFA, Cables, Camera (optional)	Kit Contents

Internal Antennas



Ezurio offers the most innovative portfolio of cost-effective internal antenna solutions that provide unmatched connectivity for your wireless IoT devices, pre-certified for use with our wireless modules. Whether for Wi-Fi/ Bluetooth or Multiband/Cellular IoT applications, the small size and form factor of Ezurio antennas make them easily concealable within a product's enclosure, eliminating any negative impact on product aesthetics.

Most available with 80, 100, and 120mm cables with MHF1/U.FL, MHF4L, and more. Additional options available on request.

Technology	Family Name	Freq (MHz)	Unique Advantage
Wi-Fi, Bluetooth, 802.15.4	FlexPIFA Single Band	2.4 GHz	Industry-first patented, flexible, adhesive-backed PIFA-style antenna with single, dual, and 6E solutions.
	FlexPIFA Dual Band	2.4/5 GHz	
	FlexPIFA 6E	2.4/5/6 GHz	
	i-FlexPIFA Single Band	2.4 GHz	Inverted, radiates on the adhesive side for mounting inside enclosures.
	i-FlexPIFA Mini	2.4 GHz	Inverted FlexPIFA at minimal size.
	FlexMIMO	2.4/5 GHz	The world's first and only MIMO PIFA antenna in dual-band and Wi-Fi 6E.
	FlexMIMO 6E	2.4/5/6 GHz	
	mFlexPIFA, peel-and-stick on metal	2.4 GHz	Industry-first patented, flexible, adhesive-backed PIFA-style Antenna optimized for placement on metal.
		2.4/5 GHz	
	Mini NanoBlade Flex	2.4/5 GHz	Flexible omnidirectional PCB Mini NanoBlade with Wi-Fi 6E offering. Excellent efficiency for size.
	Mini NanoBlade Flex 6E	2.4/5/6 GHz	
	Mini NanoBlade	2.4/5 GHz	Dual-band, vertically-polarized flexible omni PCB. Smaller than Nanoblade.
	NanoBlue	2.4 GHz	Patented Microsphere PCB technology. Integrated ground plane.
	NanoBlade	2.4/5 GHz	Dual-band, 0.1mm thick, for wearable, thin devices. Easy integration.
	FlexNotch	2.4 GHz	Adhesive flex notch antenna, custom-trimmed for max range in your enclosure.
ISM, 868/915 MHz, 2G/3G	FlexDIPOLE	863-928	Sub-GHz small form factor dipole antenna with a single antenna coverage of entire 863-928 MHz band.
	FlexPIFA 868/915	863-870 902-928	Sub-GHz flexible PIFA antenna for applications like LoRaWAN.
	i-FlexPIFA 868/915	863-870 902-928	Inverted flexible FlexPIFA antenna for LoRaWAN. Radiates on the adhesive side for mounting inside top of product enclosures.
LTE, Cat M1, NB-IoT, 5G (2G, 3G, 4G)	Revie 700 (Flex)	698-6000	96 mm long antenna for 5G sub-6GHz devices.
	Revie 600 (Flex)	600-5925	Powerful, full-spectrum antenna to support global cellular 5G networks. Some of the highest efficiencies in the market.
	Base Revie(Flex)	698-875, 1710-2500	Built specifically to support LTE-M and NB-IoT.
Ultra-Wideband (UWB)	NanoUWB	5850-8250	Planar monopole to support UWB protocol.

RF Requirements					
Dimensions (mm)	VSWR	Peak Gain (dBi)	Average Gain (dBi)	Efficiency, %	
11 x 40.1 x 2.5	< 2.0:1	2.0	> -1.5	-	
12.7 x 38.6 x 2.5	< 2.5:1, < 3.0:1	2.5, 3.0	> -2.5, > -3.4	-	
16 x 36 x 2.5	< 2.5:1, < 3.0:1, < 3.0:1	2.2, 3.9, 3.8	-	59, 60, 60	
2.9 x 11 x 40.9	< 2.5:1	3.1	-	-	
2.9 x 11 x 35.9	< 2.5:1	2.0	-	-	
33.25 x 33.25 x 4.44	< 2.3:1	2.0, 3.0	1.7, 2.5	-	
39.5 x 39.5 x 4.7	< 2.5:1	2.2, 3.8, 3.3	-	64.7, 62.3, 52.2	
25.4 x 23.4 x 2.5	< 3.0:1	2.0	> -4.2 dBi	-	
29.5 x 26.5 x 2.6	< 2.5:1, < 3.0:1	2.0, 5.8	1.9 dBi, 5.2 dBi	-	
12 x 36 x 0.1	< 2.0:1	-	2.8, 3.4	68, 59	
12 x 36 x 0.3	< 2.0:1	2.4, 4.4, 5.2	2.0, 3.5, 4.6	68, 76, 74	
12.1 x 36.1	< 2.0:1	2.5, 4.8	2.25, 3.65	-	
12.7 x 44.45 x 0.81	< 2.5:1	-	2	-	
50.8 x 1.65 x 0.1	(2:1)	-	2, 3.9, 4	-	
21.1 x 32	< 2.5:1	2.0	> -1.6	-	
75.8 x 13.75 x 0.1	863-870 MHz : < 3.0:1 902-928 MHz: < 3.0:1	863-870 MHz : 1.9 902-928 MHz : 2.4	-	-	
40 x 88 x 6.2	< 2.5:1	-1.1 (868 MHz) -0.3 (915 MHz)	-	-	
40 x 88 x 6.2	< 2.5:1	-0.4 (868 MHz) +1.9 (915 MHz)	-	-	
21 x 96 x 0.2	2.5, 2.5, 2.0, 2.5	-	-	51, 80	
30 x 130 x 0.3	2.5, 2.0, 2.0, 2.2	4.3, 3.4, 3.3, 6.0	-	62, 82, 85, 74	
20 x 90 x 0.16	2.5:1	1.9, 3.7	-	51, 80	
20 x 15 x 1.67	< 2.5:1	+3.9	-	64	

LoRaWAN IoT Devices



Ezurio's portfolio of LoRaWAN sensors and gateways delivers high performance with unparalleled design flexibility. These innovative solutions enable simple out-of-the-box integration and provide everything needed to create a complete end-to-end IoT network. Wirelessly connect battery operated wireless devices to the internet in regional, national, or global networks.

LoRaWAN Gateway		LoRaWAN Sensors			
					
Sentrius™ RG1xx Gateway and RG191 + LTE (US only)		NEW: Sentrius™ RS26x with Internal or External Temp Probe			
Chipset	 Sx1301/1257, CSR8811, QCA6004 (LTE version: Quectel EG91-NA)		  Sx126x Silicon Labs EFR32BG24		
	LoRaWAN + Wi-Fi (Optional LTE Cat 1, US only)		LoRaWAN Bluetooth LE		
Sensor Type	—		Temperature (via internal or external temp probe)		
Size (mm)	133 x 275 x 30		28.5 x 93.9 x 51.9		
Operating Temp	-30° to +70°C		-40° to +85°C		
Sensor Temp	N/A		-40° to +125°C		
Software	Onboard configuration and management software		Smartphone app for config and monitoring		
IP Rating	IP67 variant available		IP67		
Certifications	FCC, IC, CE, UKCA, RCM, NCC, and BT SIG		FCC, IC, CE, UKCA, RCM, and BT SIG. and Food Contact Safe		

LoRaWAN Sensors			
   			
Sentrius™ RS1xx Temp Sensor	Sentrius™ RS1xx and External Temp Probe	Sentrius™ RS1xx and RTD Temp Probe	Sentrius™ RS1xx and Open/Close Sensor
 Sx1272 Nordic nRF51822	  Sx1272 Nordic nRF51822		
	Sx1272 Nordic nRF51822		
LoRaWAN Bluetooth LE	LoRaWAN Bluetooth LE	LoRaWAN Bluetooth LE	LoRaWAN Bluetooth LE
Integrated Temperature & Humidity	Temperature (via external temp probe)	Temperature (via RTD Temp Probe)	Door Open/Closed (via external assembly)
116 x 91 x 34	116 x 91 x 34	116 x 91 x 34	116 x 91 x 34
-25° to +50°C	-25° to +50°C	-25° to +50°C	-25° to +50°C
-40° to +125°C	-55° to +125°C	Low Temp: -100° to +125°C Mid Temp: -40° to +180°C High Temp: -50° to +450°C	-40° to +125°C
Smartphone app for config and monitoring	Smartphone app for config and monitoring	Smartphone app for config and monitoring	Smartphone app for config and monitoring
IP67	IP67	IP67	IP67
FCC, IC, CE, UKCA, RCM, NCC, and BT SIG	FCC, IC, CE, UKCA, RCM, NCC, and BT SIG	FCC, IC, CE, UKCA, RCM, NCC, and BT SIG	FCC, IC, CE, UKCA, RCM, NCC, and BT SIG

LoRaWAN

Our LoRaWAN modules leverage years of RF expertise into a low power, long range solution for you to easily develop your LoRaWAN implementation. The LoRaWAN protocol targets key IoT requirements such as bi-directional communication, end-to-end security, mobility, and localization services. Our LoRaWAN modules deliver high performance with unparalleled design flexibility.

Modules not
actual size.



	RM126x Series
Chipset	Silicon Labs EFR32 SOC Semtech SX126x radio
Technology	LoRa™
Protocol	LoRaWAN A/B/C / LoRa P2P
Physical Interface	SMT
Frequency	RM1262: 902-928 MHz RM1261: 863-870 MHz / 902-928 MHz (see below for certified regions)
Range (Line of Sight)	Up to 15km
Size (mm)	14 x 13 x 2.5
RF Rate	LoRa: 125/250/500kHz, FSK 50kbps
Output Power	RM1262 – Up to 22dBm RM1261 – Up to 14dBm
Receiver Sensitivity	-125.6 dBm (SF7, 125kHz, 903.0MHz) -139.2 dBm (SF12, 125kHz, 863.1MHz) -122.7 dBm (SF7, 250kHz, 869.9MHz) -130.8 dBm (SF12, 500kHz, 923.3MHz)
Temp. Range (Operational)	-40° to +85°C
Software	Hosted mode using AT Command set or Hostless mode using Native C code development with Simplicity Studio
Certifications	RM1262: FCC, ISED, RCM RM1261: EU, UKCA, NCC, MIC, IN
Interface Buffer	N/A
Supply Voltage	2V-3.6V (Nominal 3.3V)

RAMP



Range Amplified MultiPoint (RAMP) modules provide the perfect solution for machine-to-machine (M2M) applications where the need is to transmit serial data or sensor data over long distances, wirelessly, with the highest degree of reliability. RAMP modules utilize FHSS technology to provide immunity to interference and multipath in industrial applications. They are capable of operating in a point-to-point or point-to-multipoint network and can support a virtually unlimited number of nodes in a network.



Modules not a
ctual size.

	RM024	
	TI CC2510	Chipset
	FHSS	Technology
	Server/Client (P2P & P2MP)	Protocol
	SMT or Pluggable	Physical Interface
	2.4 GHz	Frequency
	Up to 4 km (US) Up to 1 km (EU)	Range (Line of Sight)
	25.4 x 39 x 3.6 mm	Size
	280 kbps/500 kbps	RF Rate
	Up to 21 dBm (US) 10 dBm (EU)	Output Power
	500 kbps -88 dBm 280 kbps -92 dBm FEC 500 kbps -91 dBm FEC 280 kbps -95 dBm	Receiver Sensitivity
	-40° to +85°C	Temp. Range (Operational)
	Config and Test Utility	Software
	FCC, IC, RCM (125 mW) CE, UKCA, MIC, KC, NCC, RCM (10 mW)	Certifications
	N/A	Interface Buffer
	2.3-3.6 V ± 50 mV ripple	Supply Voltage

Software That Fits Your Environment.

One Vendor. Full Stack. No Compromises.

EZ BSP

Ezurio Board Support Package

The compute foundation. EZ BSP is the anchor of your compute architecture – the software layer that sits between silicon vendor BSPs (NXP, TI, MediaTek) and your application, delivering secure, production-ready compute from day one. Reproducible Yocto builds, HRoT provisioning, verified boot, OTA integrity, and a 5-year binary guarantee. Where your compute starts is where Ezurio begins.



Chain of Trust



FIPS Cryptographic Modules



Security BSP Releases

EZ Connectivity Stack

Not just a driver. The whole stack.

The wireless software layer that fits your environment – not the other way around. 75+ kernel versions supported (v2.6–v6.12+), bi-annual CVE releases, WPA3 Enterprise + EAP-FAST, and Adaptive Worldwide Mode. When an Ezurio Wi-Fi module is in your SOM, the full connectivity stack comes with it – one vendor for silicon and software.



Adaptive Worldwide Mode



Kernel Backports

Software That Fits Your Environment.

One Vendor. Full Stack. No Compromises.

EZ MCP

AI-assisted coding, integration, and troubleshooting

The Ezurio MCP (Model Context Protocol) connects AI development tools to Ezurio documentation, SDKs, APIs, hardware specifications, code examples, and integration guides, enabling more accurate code generation, faster troubleshooting, and product-specific guidance across Ezurio's wireless, embedded, edge AI, and IoT solutions.



Natural Language Support



Faster Integration



Context-Specific Troubleshooting



Governed AI Workflows

Canvas™ Software Suite

Get to market faster

Build wireless IoT applications in days, not months. Run embedded Python directly on the module—no vendor-specific SDKs or embedded C. Canvas firmware provides portable wireless APIs across chipsets, while Canvas Tools for VS Code, Desktop, and Mobile simplify development, debugging, and testing. Start with portable Python sample apps, customize for your use case, and update firmware and scripts wirelessly.



Firmware



Tools



Samples



Docs

For more information about Ezurio products and services, visit our web site at www.ezurio.com



Simplify Connectivity & Compute

2026_V2